Silicon P-Channel MOS FET

HITACHI

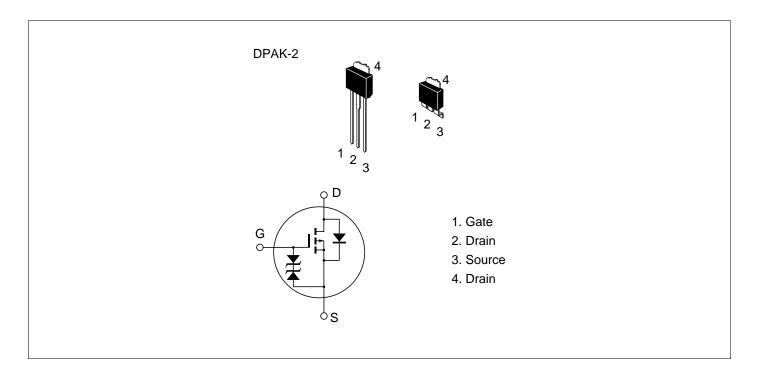
Application

High speed power switching

Features

- Low on-resistance
- Low drive current
- 2.5 V Gate drive device can be driven from 3 V Source
- Suitable for Switching regulator, DC DC converter

Outline





Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{\scriptscriptstyle DSS}$	-20	V
Gate to source voltage	V _{GSS}	±10	V
Drain current	I _D	– 10	A
Drain peak current	I _{D(pulse)} *1	-40	A
Body to drain diode reverse drain current	I _{DR}	-10	A
Channel dissipation	Pch*2	20	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

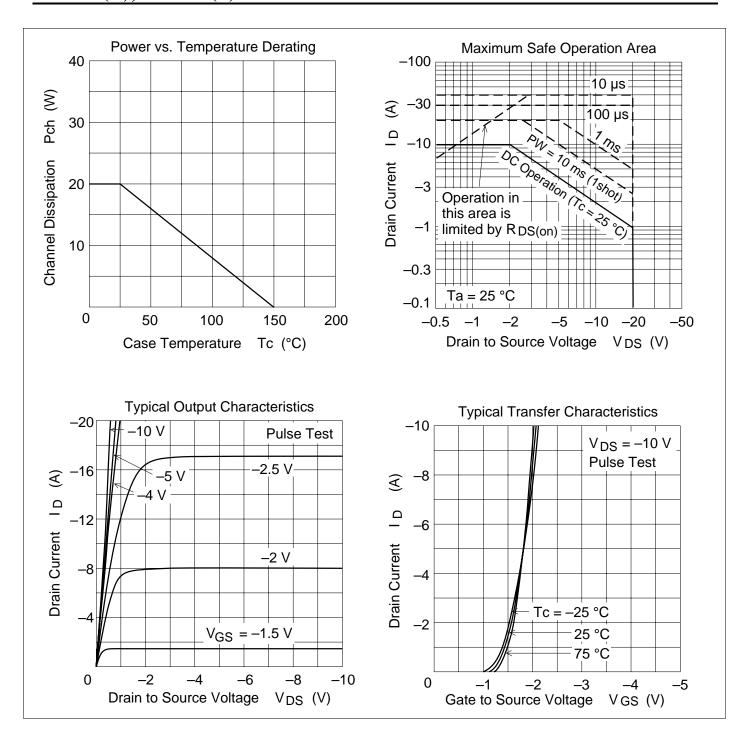
Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

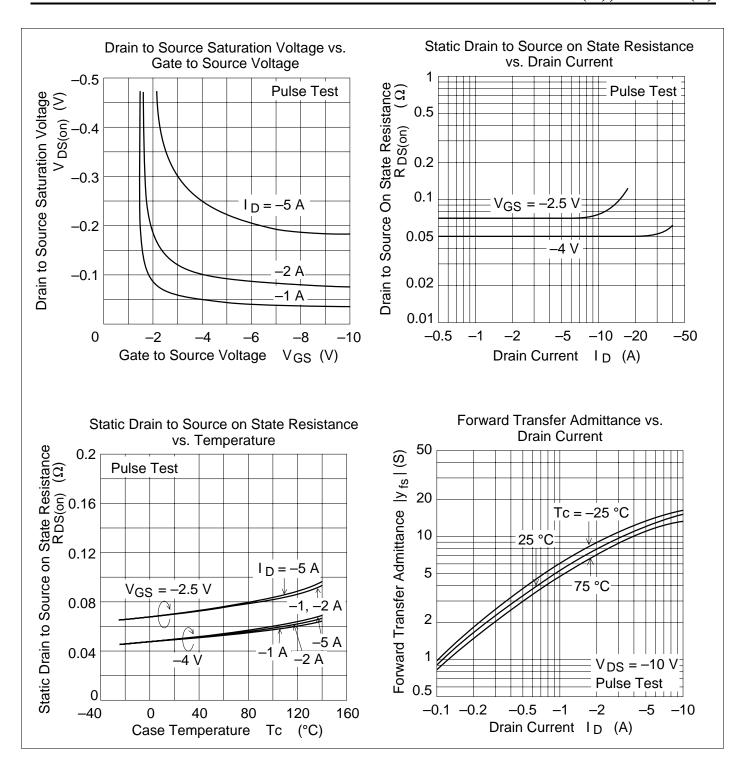
2. Value at Tc = 25°C

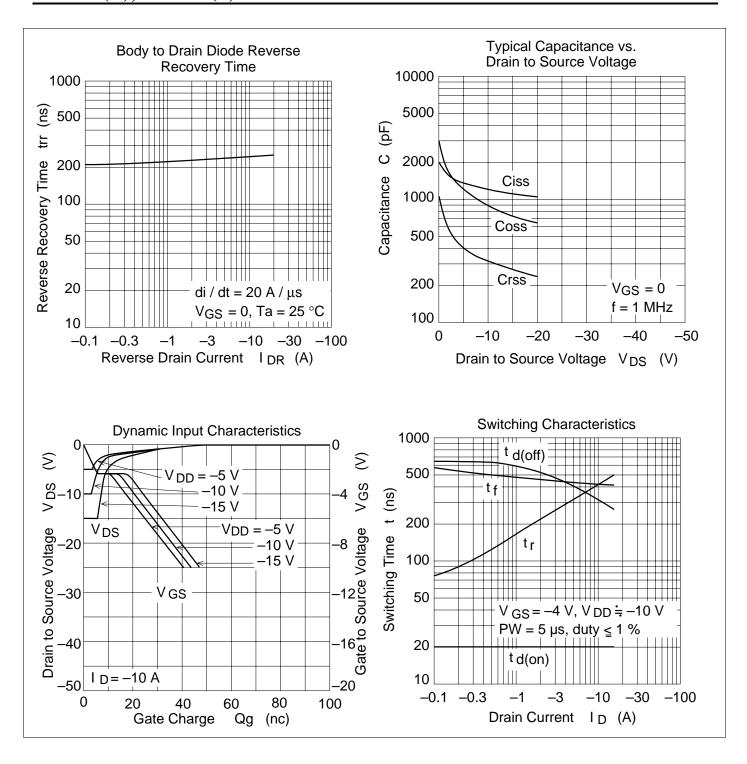
Electrical Characteristics (Ta = 25°C)

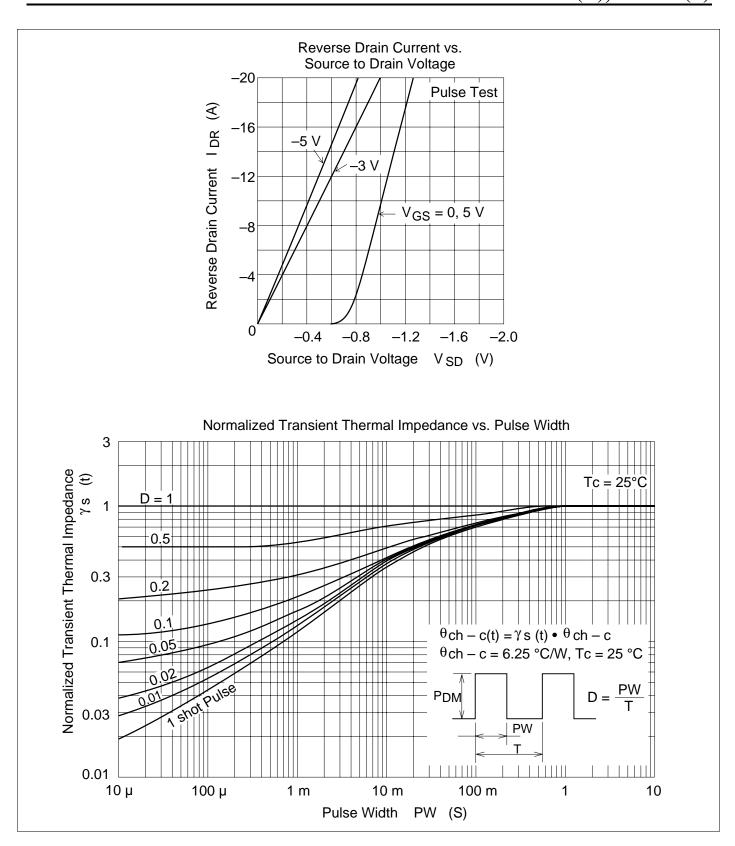
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-20	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±10	_	_	V	$I_{G} = \pm 200 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 6.5 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-100	μΑ	$V_{DS} = -16 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-0.5	_	-1.5	V	$I_{D} = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	$R_{\scriptscriptstyle DS(on)}$	_	0.05	0.07	Ω	$I_{D} = -5 \text{ A}$ $V_{GS} = -4 \text{ V}^{*1}$
		_	0.07	0.1	Ω	$I_D = -5 \text{ A}$ $V_{GS} = -2.5 \text{ V}^{*1}$
Forward transfer admittance	y _{fs}	7	12	_	S	$I_D = -5 \text{ A}$ $V_{DS} = -10 \text{ V}^{*1}$
Input capacitance	Ciss	_	1170	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	860	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	310	_	pF	f = 1 MHz
Turn-on delay time	$t_{d(on)}$	_	20	_	ns	$I_D = -5 A$
Rise time	t_{r}	_	325	_	ns	$V_{GS} = -4 V$
Turn-off delay time	t _{d(off)}	_	350	_	ns	$R_L = 2 \Omega$
Fall time	t _f		425	_	ns	
Body to drain diode forward voltage	V_{DF}		-1.0		V	$I_F = -10 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	240	_	ns	$I_F = -10 \text{ A}, V_{GS} = 0,$ diF/dt = 20 A/ μ s

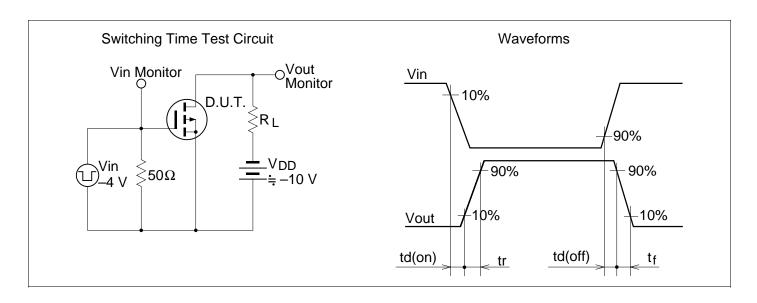
Note: 1. Pulse Test



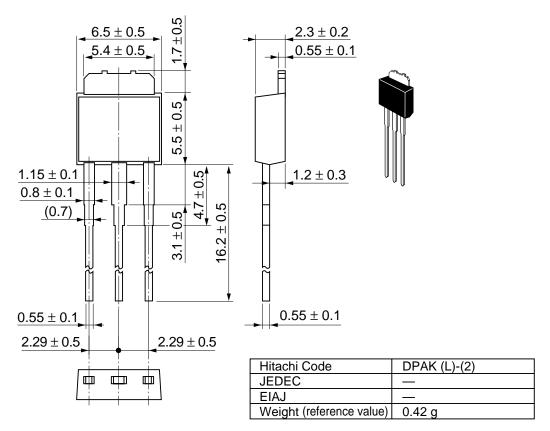








Unit: mm



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